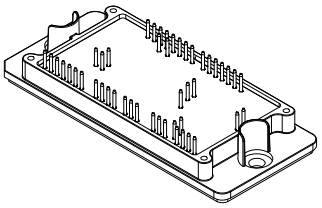
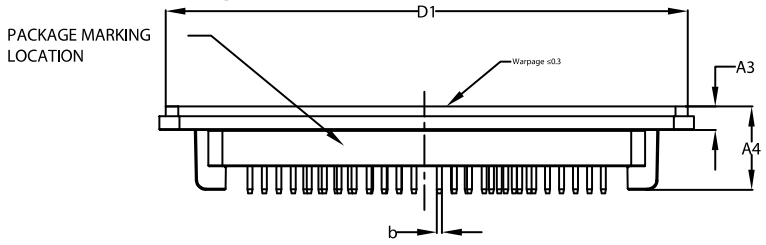
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

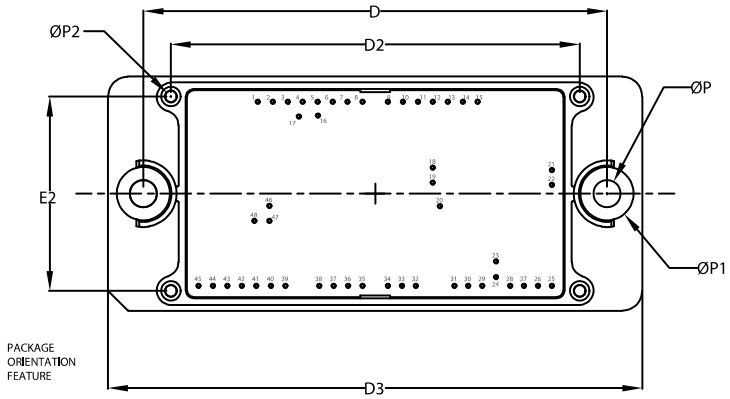
PIM48, 93x47 (SOLDER PIN)
CASE 180BL
ISSUE A

DATE 08 DEC 2022

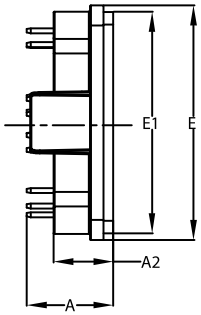




SIDE VIEW



TOP VIEW



END VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009
2. CONTROLLING DIMENSION : MILLIMETERS
3. DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A1
4. PIN POSITION TOLERANCE IS ± 0.4mm
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	16.80	17.20	17.60
A2	11.70	12.00	12.30
A3	4.40	4.70	5.00
A4	16.40	16.70	17.00
b	0.95	1.00	1.05
D	92.90	93.00	93.10
D1	104.45	104.75	105.05
D2	81.80	82.00	82.20
D3	106.90	107.20	107.50
E	46.70	47.00	47.30
E1	44.10	44.40	44.70
E2	38.80	39.00	39.20
P	5.40	5.50	5.60
P1	10.60	10.70	10.80
P2	1.80	2.00	2.20

S Pin position

Pin table				Pin table			
Pin	X	Y	Function	Pin	X	Y	Function
1	11.9	36.9	Phase1	25	70.9	0	DC-
2	14.9	36.9	Phase1	26	68.1	0	DC-
3	17.9	36.9	Phase1	27	65.3	0	DC-
4	20.9	36.9	Phase1	28	62.5	0	DC-
5	23.9	36.9	Phase1	29	56.9	0	DC-
6	26.9	36.9	Phase1	30	54.1	0	DC-
7	29.9	36.9	Phase1	31	51.3	0	DC-
8	32.9	36.9	Phase1	32	43.6	0	N2
9	38	36.9	Phase2	33	40.8	0	N2
10	41	36.9	Phase2	34	38	0	N2
11	44	36.9	Phase2	35	32.9	0	N1
12	47	36.9	Phase2	36	30	0	N1
13	50	36.9	Phase2	37	27.1	0	N1
14	53	36.9	Phase2	38	24.2	0	N1
15	56	36.9	Phase2	39	17.4	0	DC+
16	23.95	34.1	E2	40	14.5	0	DC+
17	20.15	33.9	G2	41	11.6	0	DC+
18	47	23.65	G3	42	8.7	0	DC+
19	47	20.65	E3	43	5.8	0	DC+
20	48.4	15.95	N	44	2.9	0	DC+
21	70.9	23.2	TH1	45	0	0	DC+
22	70.9	20.2	TH2	46	14.2	16	P
23	59.7	4.85	G4	47	14.2	13	E1
24	59.7	1.75	E4	48	11.2	13	G1

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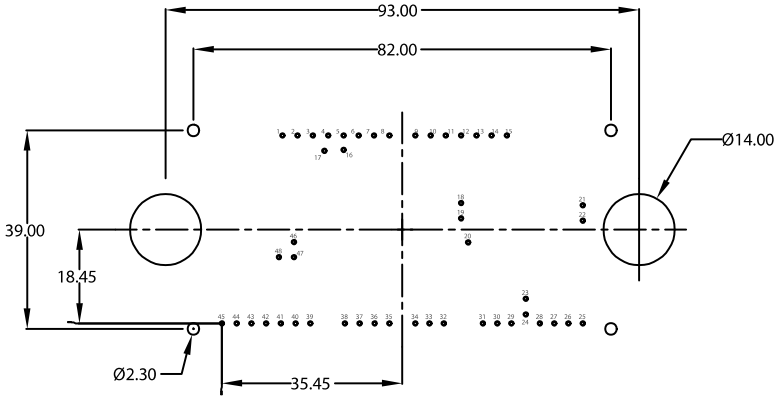
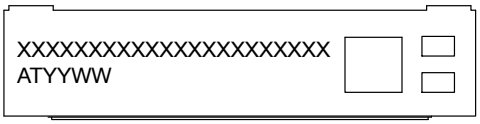


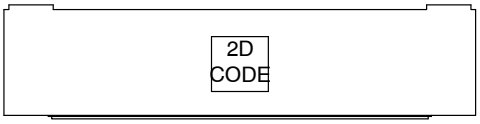
RECOMMENDED
MOUNTING PATTERN

* For additional Information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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